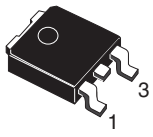
STD96N3LLH6

N-channel 30 V, 0.0037 Ω, 80 A, DPAK STripFET™ VI DeepGATE™ Power MOSFET

Features

Type	V_{DSS}	$R_{DS(on)}$ max	I_D
STD96N3LLH6	30 V	0.0042 Ω	80 A

- $R_{DS(on)}$ * Q_g industry benchmark
- Extremely low on-resistance $R_{DS(on)}$
- High avalanche ruggedness
- Low gate drive power losses



DPAK

Application

- Switching applications
  - Automotive

Description

This product is an N-channel Power MOSFET that utilizes the 6th generation of design rules of ST's proprietary STripFET™ technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest $R_{DS(on)}$ in all packages.

Figure 1. Internal schematic diagram

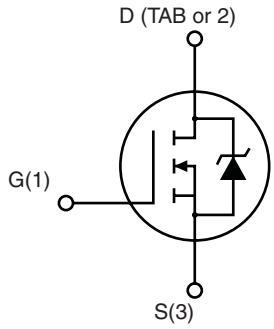


Table 1. Device summary

Order codes	Marking	Package	Packaging
STD96N3LLH6	96N3LLH6	DPAK	Tape and reel

Contents

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0)	30	V
V_{GS}	Gate-source voltage	± 20	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	80	A
I_D	Drain current (continuous) at T_C = 100 °C	61	A
I_{DM} (2)	Drain current (pulsed)	320	A
P_{TOT}	Total dissipation at T_C = 25 °C	70	W
	Derating factor	0.47	W/°C
E_{AS} (3)	Single pulse avalanche energy	150	mJ
T_{stg}	Storage temperature	-55 to 175	°C
T_j	Max. operating junction temperature	175	°C

1. Limited by wire bonding.
2. Pulse width limited by safe operating area.
3. Starting Tj = 25°C, I_{AV} = 55 A, L = 0.1 mH

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case max	2.14	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient max	100	°C/W
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb max	35	°C/W
T_l	Maximum lead temperature for soldering purpose	275	°C

1. When mounted on FR-4 board of 1 inch^2, 2 oz Cu.

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown Voltage	I_D = 250 µA, V_{GS}= 0	30			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 30 V V_{DS} = 30 V, Tc = 125 °C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ± 20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	1		2.5	V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS} = 10 V, I_D = 40 A		0.0037	0.0042	Ω
		V_{GS} = 5.5 V, I_D = 40 A		0.0055	0.007	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min	Typ.	Max.	Unit
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 25 V, f=1 MHz, V_{GS} = 0	-	2200 400 280	-	pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 15 V, I_D = 80 A V_{GS} = 4.5 V *Figure 13*	-	20 8.2 7.5	-	nC nC nC
Q_{gs1} Q_{gs2}	Pre V_{th} gate-to-source charge Post V_{th} gate-to-source charge	V_{DD} = 15 V, I_D = 80 A *Figure 18*	-	3.4 6.2	-	nC nC
R_G	Gate input resistance	f = 1 MHz gate bias Bias = 0 test signal level = 20 mV open drain	-	1	-	Ω

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	V_{DD} = 15 V, I_D = 40 A, R_G = 4.7 Ω, V_{GS} = 5 V *Figure 12*	-	19 91	-	ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time	V_{DD} = 15 V, I_D = 40 A, R_G = 4.7 Ω, V_{GS} = 5 V *Figure 12*	-	24.5 23.4	-	ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM}(1)	Source-drain current Source-drain current (pulsed)		-		80 320	A A
V_{SD}(2)	Forward on voltage	I_{SD} = 40 A, V_{GS} = 0	-		1.1	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 80 A, di/dt = 100 A/µs, V_{DD} = 24 V *Figure 14*	-	28.6 22.8 1.6		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

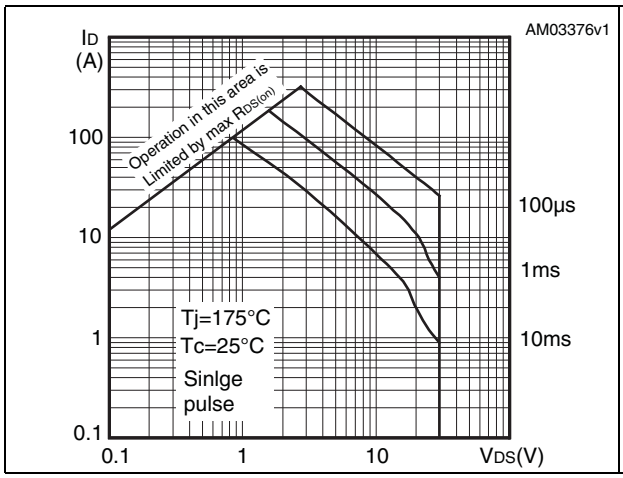


Figure 3. Thermal impedance

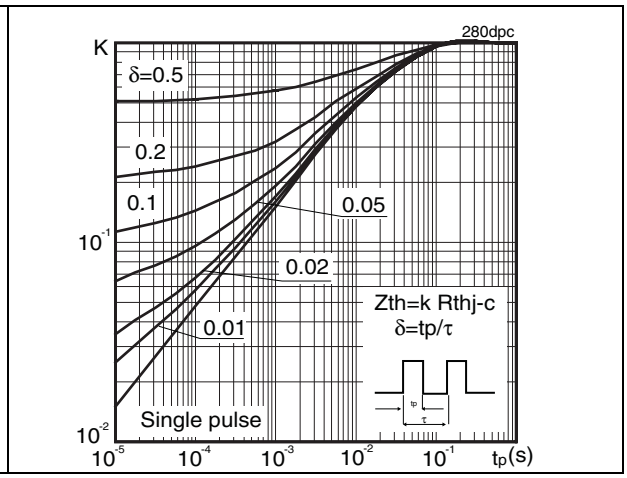


Figure 4. Output characteristics

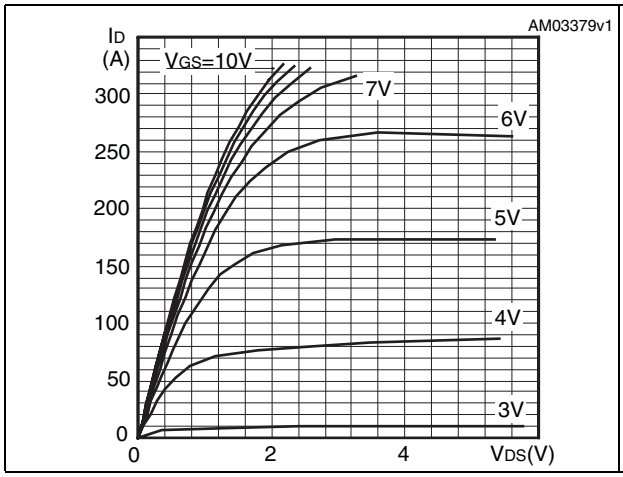


Figure 5. Transfer characteristics

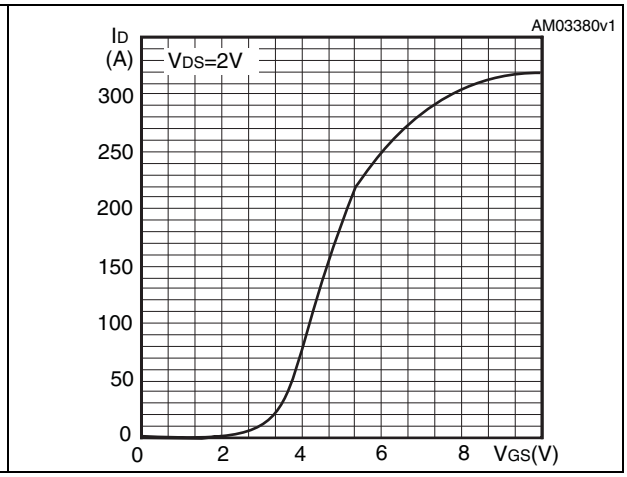


Figure 6. Normalized BV_{DSS} vs temperature

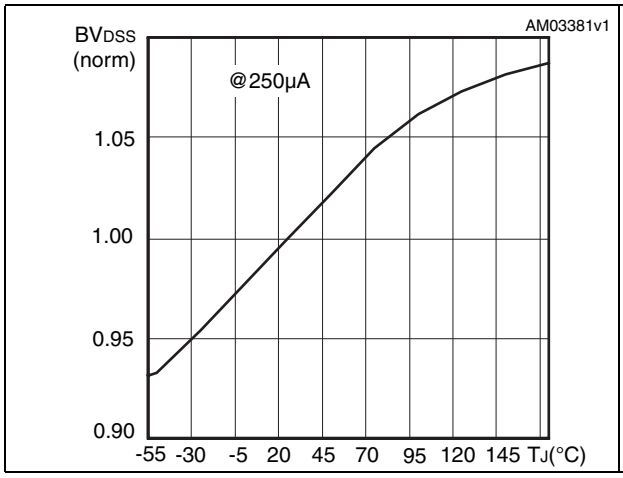


Figure 7. Static drain source on resistance

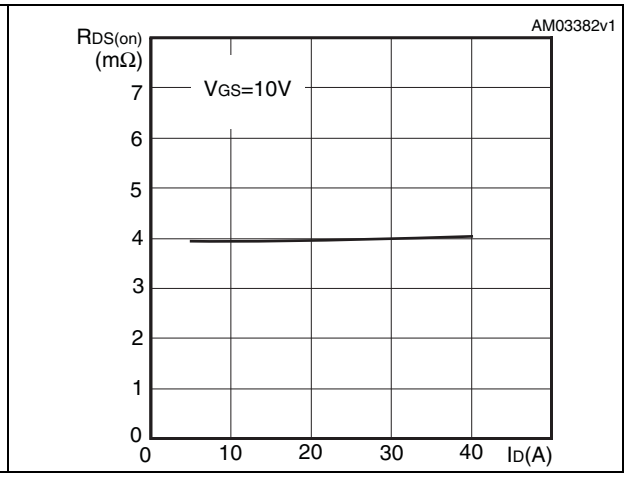


Figure 8. Gate charge vs gate-source voltage

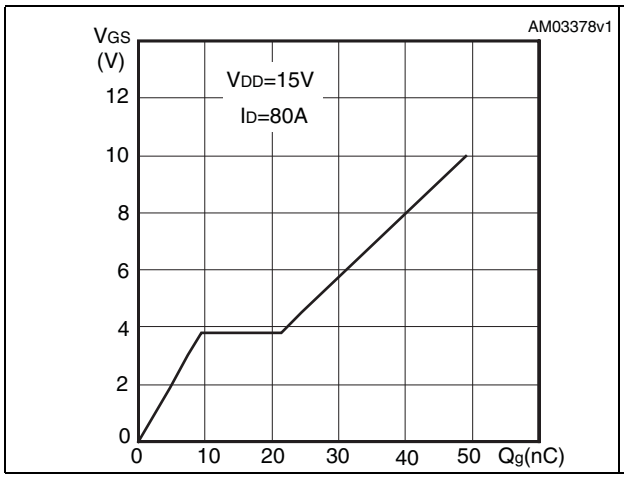


Figure 9. Capacitance variations

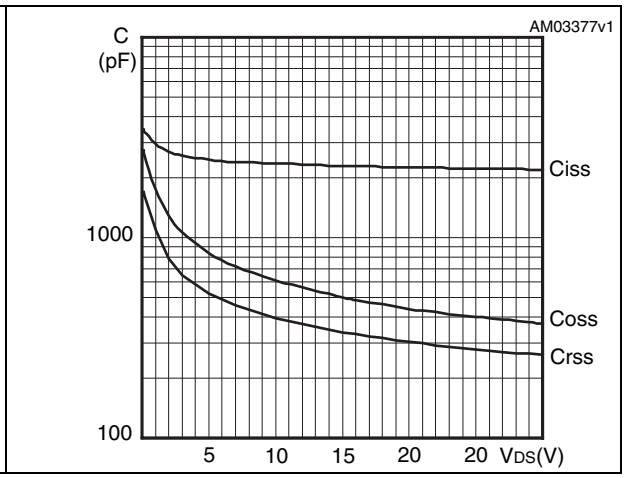


Figure 10. Normalized gate threshold voltage vs temperature

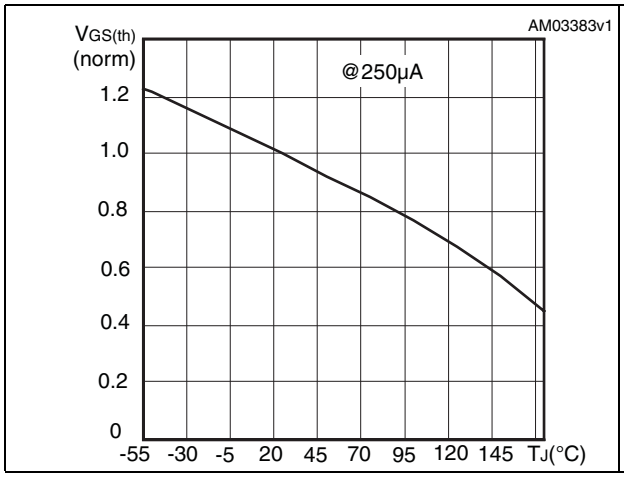
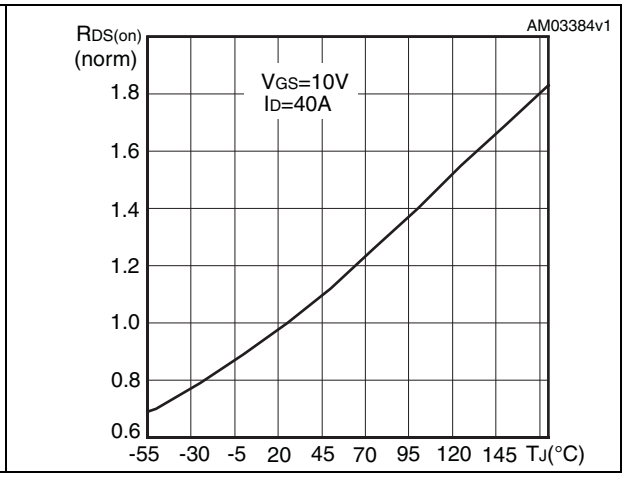


Figure 11. Normalized on resistance vs temperature



3 Test circuits

Figure 12. Switching times test circuit for resistive load

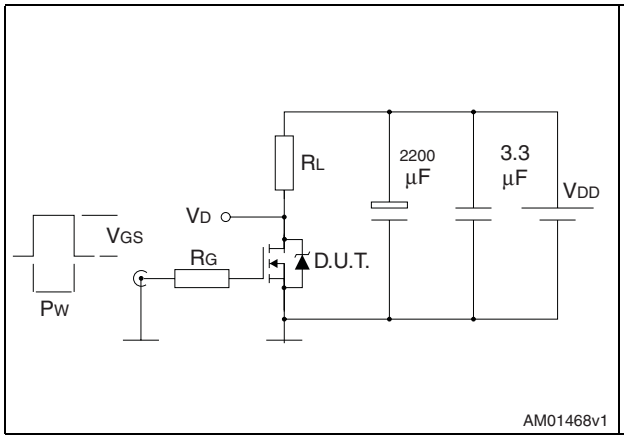


Figure 13. Gate charge test circuit

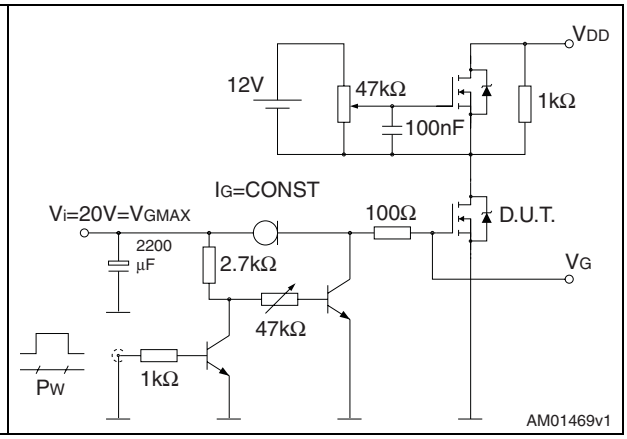


Figure 14. Test circuit for inductive load switching and diode recovery times

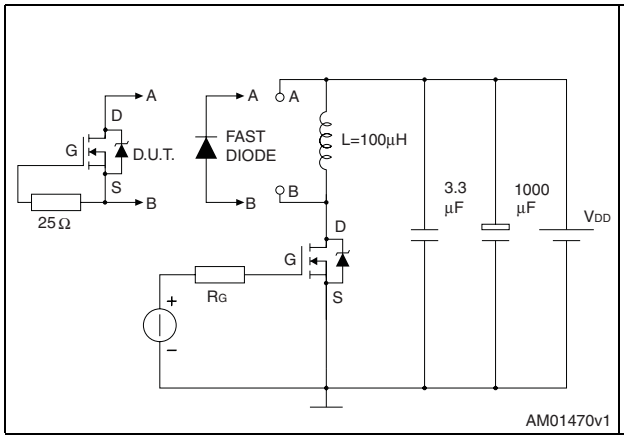


Figure 15. Unclamped inductive load test circuit

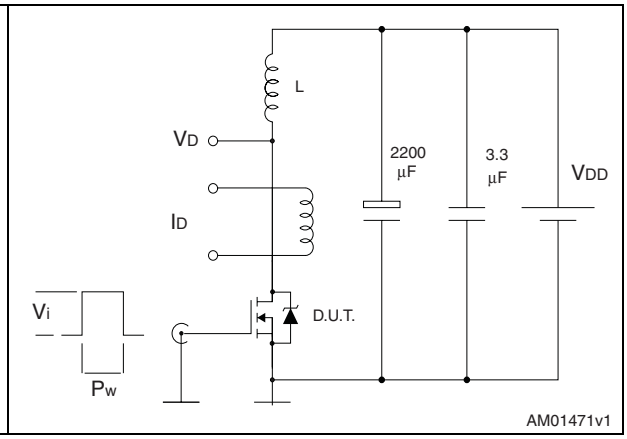


Figure 16. Unclamped inductive waveform

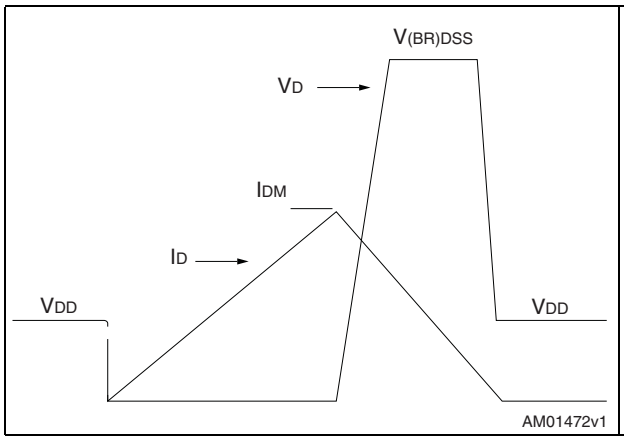


Figure 17. Switching time waveform

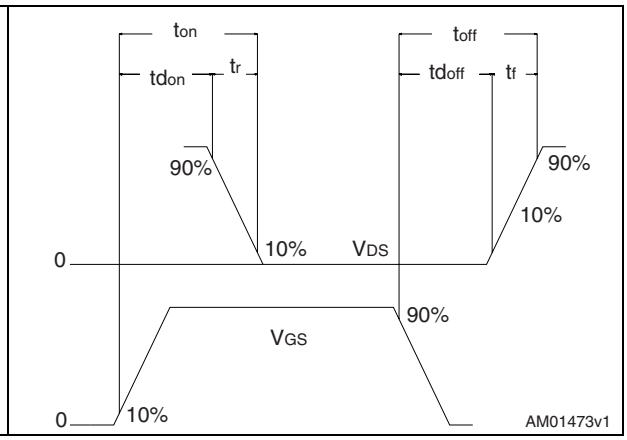
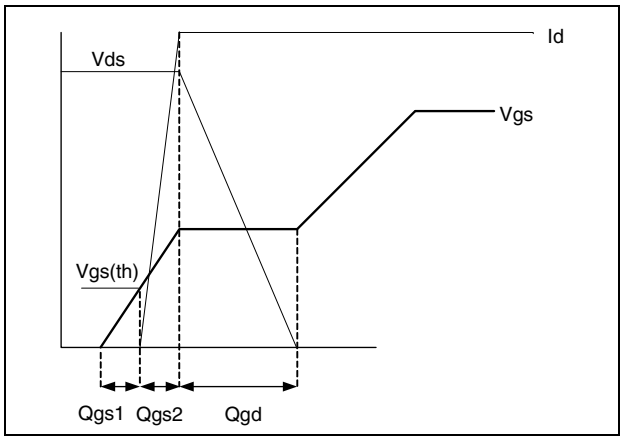


Figure 18. Gate charge waveform



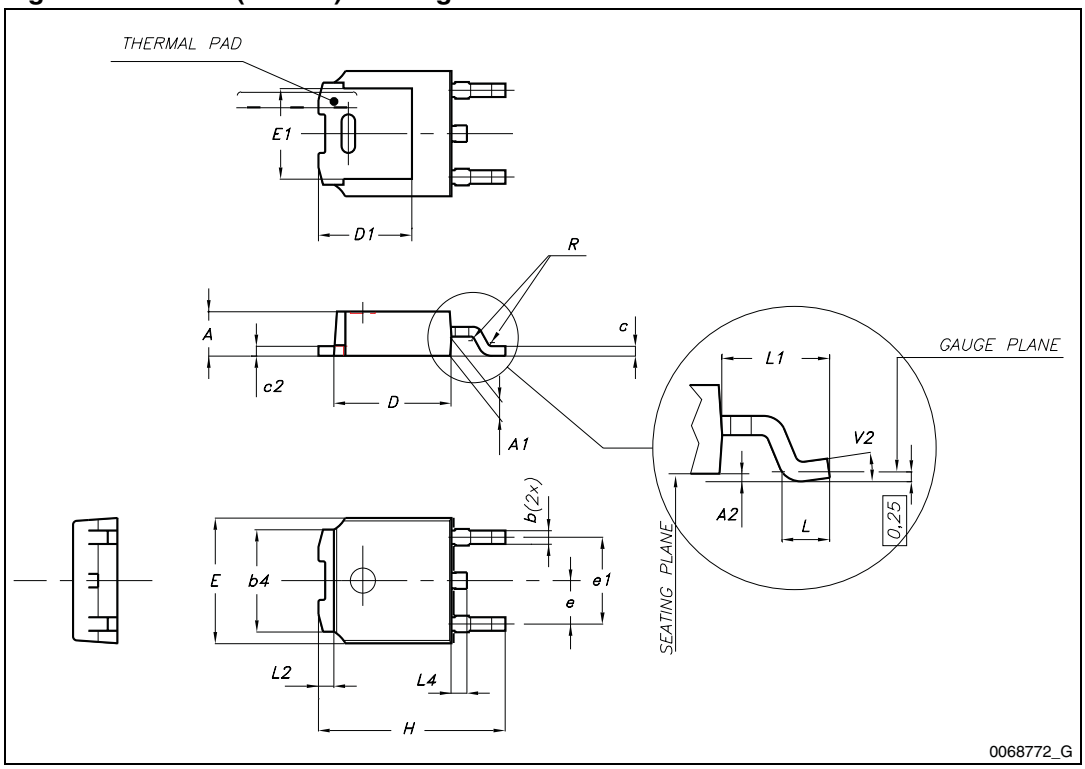
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. DPAK (TO-252) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1		
L1		2.80	
L2		0.80	
L4	0.60		1
R		0.20	
V2	0°		8°

Figure 19. DPAK (TO-252) drawing

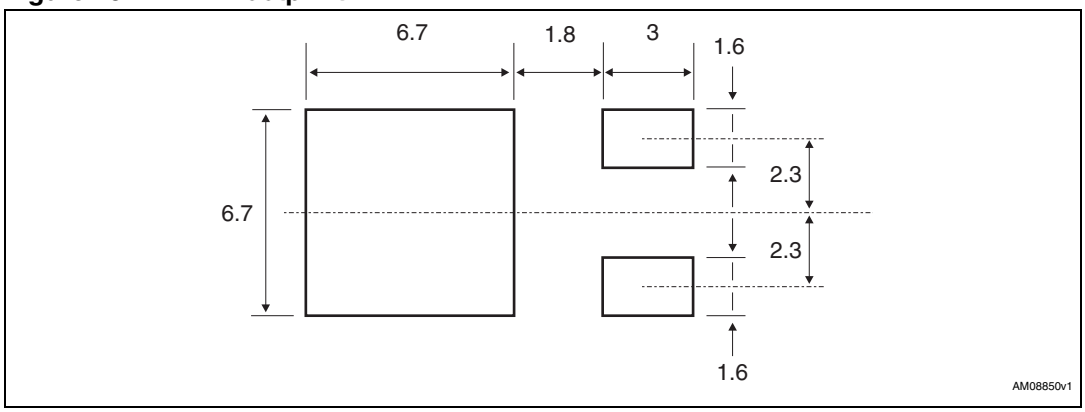


5 Packaging mechanical data

Table 9. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Figure 20. DPAK footprint[a]



a. All dimension are in millimeters

Figure 21. Tape for DPAK (TO-252)

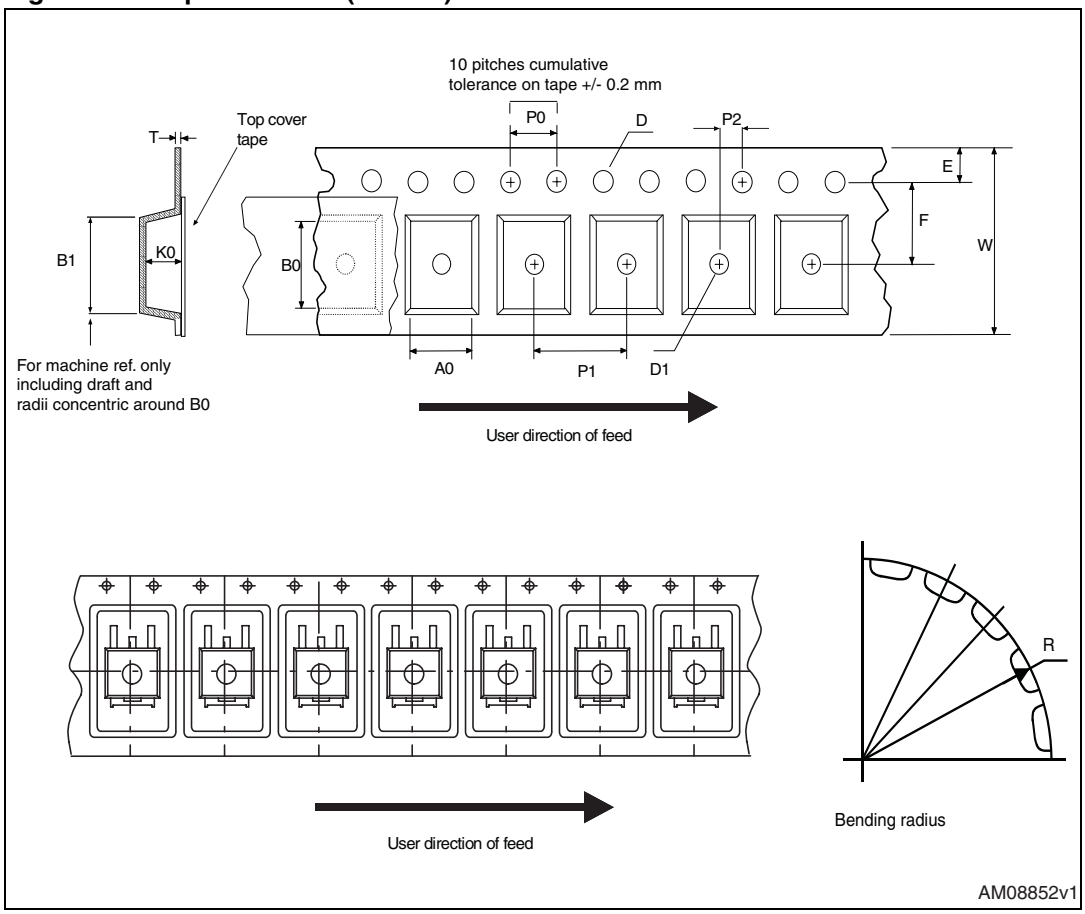
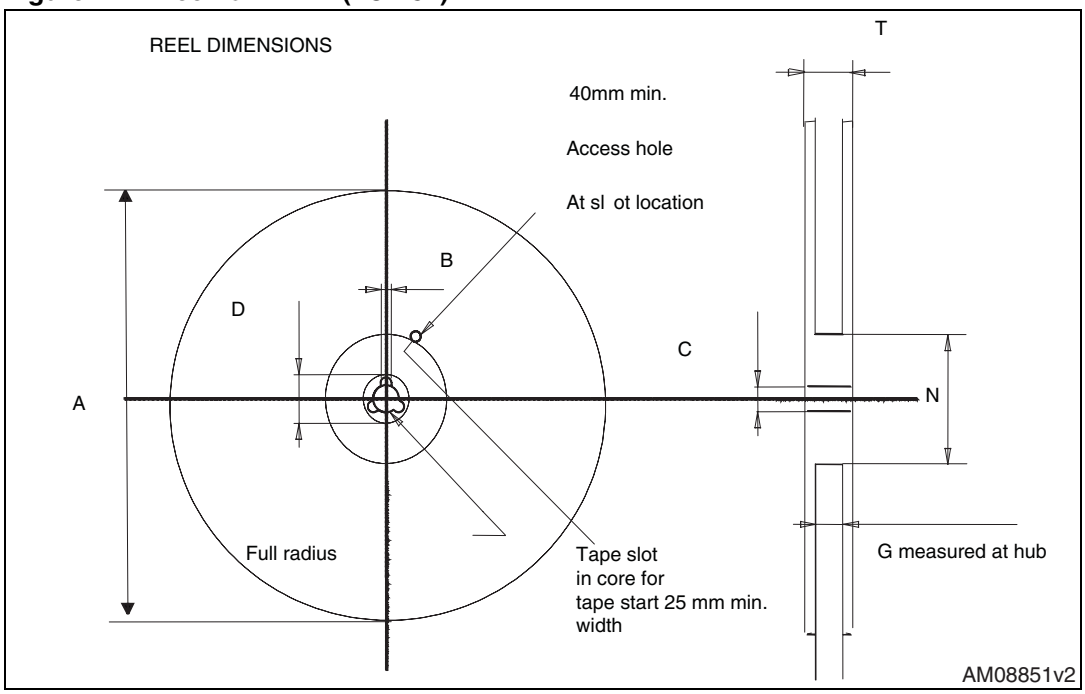


Figure 22. Reel for DPAK (TO-252)



6 Revision history

Table 10. Document revision history

Date	Revision	Changes
27-Jan-2011	1	First release.

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